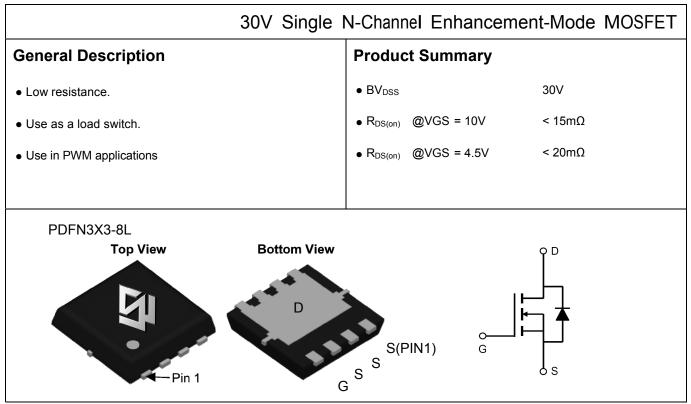


## SWD7402



Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current (T <sub>A</sub> =25°C)		10	Α
Drain Current (T <sub>A</sub> =75°C)	I <sub>D</sub>	8	Α
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	60	Α
Avalanche Energy (L= 0.1 mH)	E <sub>AS</sub>	25	mJ
Power Dissipation <sup>b</sup> (T <sub>A</sub> =25°C)	_	2	W
Power Dissipation <sup>b</sup> (T <sub>A</sub> =75°C)	PD	1.2	W
Junction and Storage Temperature Range	T <sub>J,</sub> T <sub>STG</sub>	-55 ~ +150	°C

Thermal Characteristics					
Parameter	Symbol	Maximum	Units		
Junction-to-Ambient <sup>a</sup> (t $\leq$ 10s)	5	42	°C/W		
Junction-to-Ambient <sup>a,d</sup> (Steady-State)	R <sub>eja</sub>	62	°C/W		
Junction-to-Lead (Steady-State)	R <sub>eJL</sub>	4	°C/W		



## SWD7402

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Off Char	acteristics					
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}$ = 0V , I <sub>D</sub> = 250uA	30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS}$ = 30V , $V_{GS}$ = 0V			1	uA
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{GS}$ = ±20V, $V_{DS}$ = 0V			±100	nA
On Chara	acteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}$ = $V_{GS}$ , $I_D$ = 250 $uA$	1.0	1.8	2.5	V
R <sub>DS(ON))</sub>	Drain-Source On-State Resistance	$V_{GS}$ = 10V , $I_D$ = 12A		11	15	mΩ
		$V_{GS}$ = 4.5V , I <sub>D</sub> = 9A		15	20	mΩ
<b>g</b> fs	Forward Transconductance	$V_{DS}$ = 5.0V , $I_{D}$ = 12A		35		S
Drain-So	ource Diode Characteristics					
$V_{\text{SD}}$	Diode Forward Voltage	$V_{GS}$ = 0V , I <sub>S</sub> = 1.0A			1.1	V
Is	Maximum Body-Diode Continuous Current				40	А
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 15V , V <sub>GS</sub> = 0V f = 1.0MHz		940		pF
C <sub>oss</sub>	Output Capacitance			132		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			111		pF
Switchin	g Characteristics					
Qg	Total Gate Charge			10.2		nC
$Q_gs$	Gate-Source Charge	V <sub>DS</sub> = 15V , I <sub>D</sub> = 15A V <sub>GS</sub> = 4.5V		4.3		nC
$\mathbf{Q}_{gd}$	Gate-Drain Charge			3.5		nC
t <sub>D(ON</sub> )	Turn-On Delay Time	V <sub>DD</sub> = 15V , ID = 15A V <sub>GS</sub> = 10 V R <sub>GEN</sub> = 3.3 ohm		5		ns
tr	Turn-On Rise Time			8		ns
$t_{D(OFF)}$	Turn-Off Delay Time			32		ns
t <sub>f</sub>	Turn-Off Fall Time			4		ns

a. Repetitive rating, Pulse width limited by junction temperature T<sub>J(MAX)</sub>=150 °C. Ratings are based on low frequency and duty cycles to keep initial T<sub>J</sub>=25 °C

b. The power dissipation  $P_D$  is based on  $T_{J(MAX)}\text{=}150~^{o}\text{C}$  , using  ${\leqslant}10\text{s}$  junction-to-ambient thermal resistance.

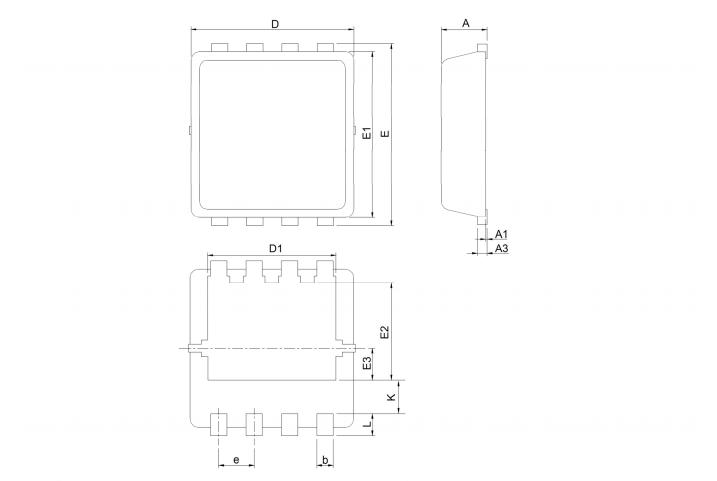
c. The value of  $R_{\theta JA}$  is measured with the device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^{\circ}$ C. The value in any given application depends on the user's specific board design.

d. The  $R_{\theta JA}$  is the sum of the thermal impedence from junction to lead  $R_{\theta JL}$  and lead to ambient.



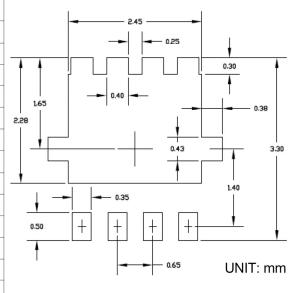


## PDFN3x3-8L Package



S	DFN3x3-8				
SYMBOL	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
А	0.80	1.00	0.031	0.039	
A1	0.00	0.05	0.000	0.002	
A3	0.10	0.25	0.004	0.010	
b	0.24	0.35	0.009	0.014	
D	2.90	3.10	0.114	0.122	
D1	2.25	2.45	0.089	0.096	
E	3.10	3.30	0.122	0.130	
E1	2.90	3.10	0.114	0.122	
E2	1.65	1.85	0.065	0.073	
E3	0.56	0.58	0.022	0.023	
е	0.65 BSC		0.020	6 BSC	
К	0.475	0.775	0.019	0.031	
L	0.30	0.50	0.012	0.020	

## **RECOMMENDED LAND PATTERN**



单击下面可查看定价,库存,交付和生命周期等信息

>>SiliconWisdom(矽睿半导体)